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TITLE: MANUFACTURE OF SEMICONDUCTOR ELEMENT

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ABSTRACT:

PURPOSE: To improve hydrolytic resistance, moisture resistance and reliability of a semiconductor element and at the same time to realize high speed assembly of the semiconductor element by a method wherein a semiconductor chip is made to adhere and fixed to a lead frame with adhesive composed of modified resin, which is composed of specific resin and epoxy resin, and inorganic filler.

CONSTITUTION: Adhesive is applied to the back of a semiconductor chip and then, in the semi-cured condition, the semiconductor chip is made to adhere and fixed to a lead frame. The adhesive consisting of resin whose main components are bismaleimide and triazine resin monomer, epoxy resin and inorganic filler is employed. The resin whose main components are bismaleimide and triazine resin monomer is the resin whose main components are bismaleimide shown by the formula I and dicyanate shown by the formula II and has triazine rings in which at least 3mol of dicyanate shown by the formula II are cyclopolymerized in its molecule and has a cyanate radical at the end of its molecule and, for instance, triazine resin shown by the formula III. By employing such adhesive, excellent hydrolytic resistance and moisture resistance are provided and, as there is not cause of erosion disconnection such as sputtering of solder, high reliability is also provided.

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